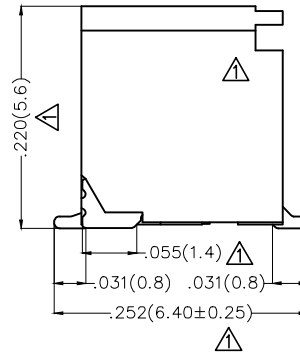
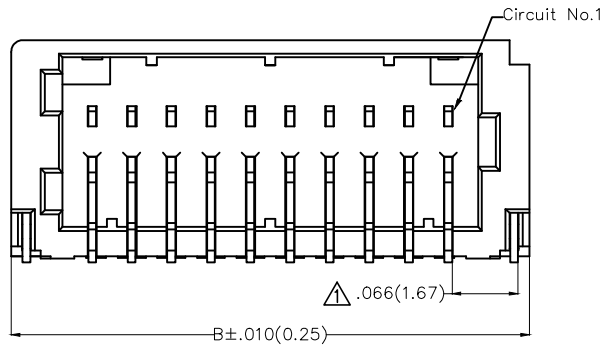
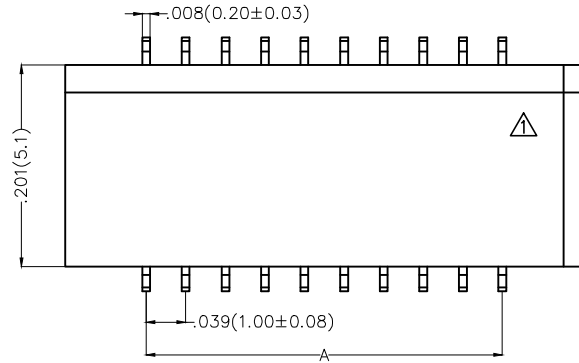


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Structural and size changes	28/APR/21	KATE	CHERRY

**Electrical**

Current Rating: 1A AC(rms)/DC(AWG32)  
Voltage Rating: 50V AC(rms)/DC  
Contact Resistance: 20 mΩ Max  
Insulation Resistance: 100 MΩ MIN  
Withstanding Voltage: 500V AC r.m.s  
Temperature Range—Operating: -25°C~+85°C  
**Material and Plating**  
Housing: PA9T ( UL 94V-0)  
Contact Pin: Brass  
Plating: Gold Plated

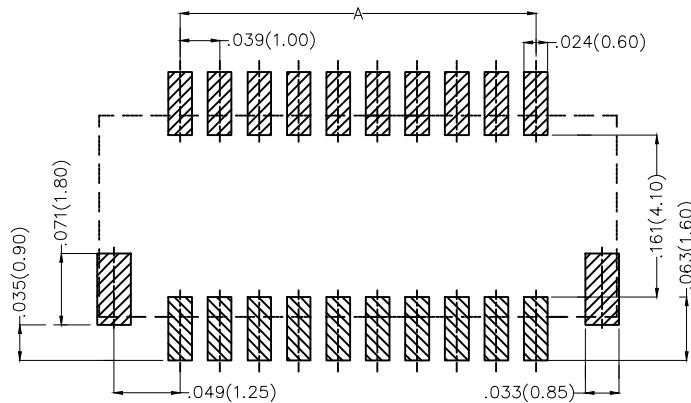


Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B △
10	FWF10004-D10B14W5M	.157(4.00)	.319(8.10)
20	FWF10004-D20B14W5M	.354(9.00)	.516(13.10)
30	FWF10004-D30B14W5M	.551(14.00)	.713(18.10)
40	FWF10004-D40B14W5M	.748(19.00)	.909(23.10)
50	FWF10004-D50B14W5M	.945(24.00)	1.106(28.10)


**Ordering Information**

FWF 100 04 — D XX B 1 4 W5 M  
1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 100-Pitch1.0mm	3 Distinction No. 04	4 Row Option D-Double Row	5 Circuits XX	6 Entry Angle B-90° Angle
7 Plating 1-Gold Plated	8 Material-Resin 4-PA9T	9 Color-Resin W5-White	10 Packaging M-Reel		



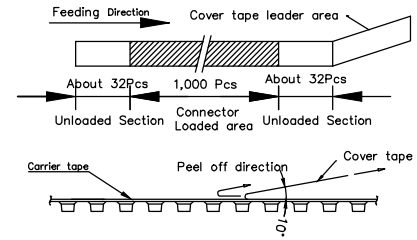
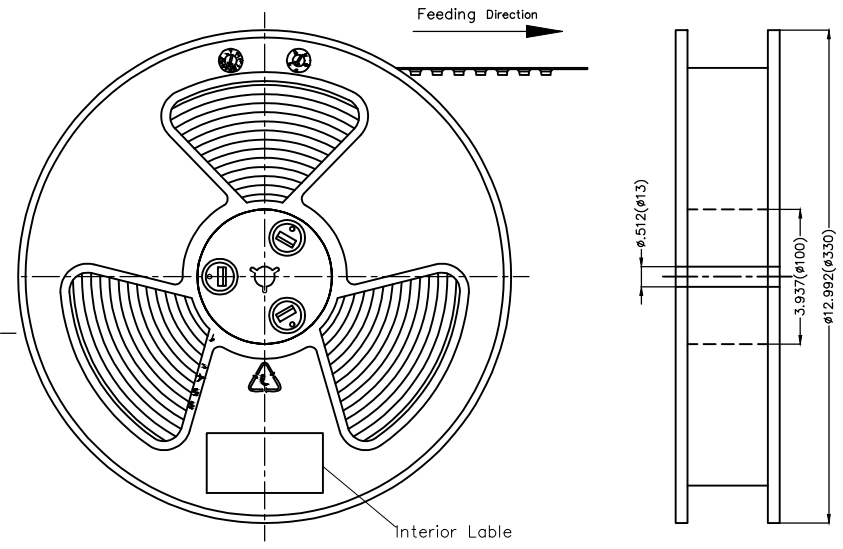
**Recommended P.C.Board Layout**  
Tolerances: ±.002(0.05)

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.±5'	FRANK	28/JUN/13	FWF10004-DXXB14W5M	
SCALE 5:1	X.X±.008(0.20)	.X'±2'	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 1.0mm 90° Angle (SMT)		REV 1
	X.XX±.006(0.15)	.XX'±1'	DRAWN BY CHERRY	DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 1/2
	X.XXX±.004(0.10)	.XXX'±0.5'					

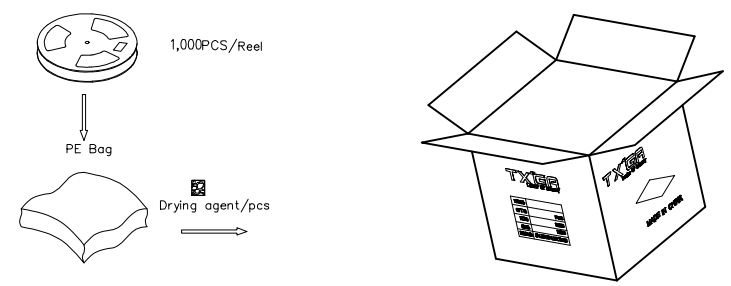
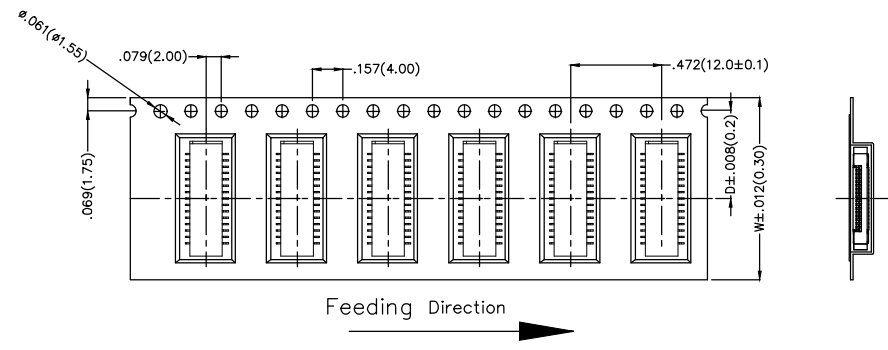
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Note:

- 10 sprocket hole cumulative tolerance  $\pm 0.2$
- Carrier camber is within 1.0mm in 250mm
- Material: White Conductive polystyrene Alloy 100% recyclable
- All dimensions meet EIA-481-3 requirements
- Peel off force of cover tape & carrier tape: 20g~130g(0.2N~1.3N)
- Component load per 13" reel: 1,000 pcs



Circuits (n)	Dimensions (in/mm)	
	D	W
10	.453(11.50)	.945(24.00)
20	.453(11.50)	.945(24.00)
30	.453(11.50)	.945(24.00)
40	.798(20.20)	1.732(44.00)
50	.798(20.20)	1.732(44.00)



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	X.±.012(0.30)	X.±5'	FRANK	28/JUN/13	FWF10004-DXXB14W5M	FWF10004	
DESIGN UNITS Inch (metric)	X.X±.008(0.20)	.X'±2'	CHECKED BY	DATE	TITLE		REV 1    SHEET NO. 2/2
SCALE	X.XX±.006(0.15)	.XX'±1'	JACOB	28/JUN/13	Wire to Board (Wafer) Pitch 1.0mm 90° Angle (SMT)		
SIZE	X.XXX±.004(0.10)	.XXX'±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		APPD
5:1	A4		CHERRY	28/JUN/13			